WHAT IS CLAIMED IS:

1. A circuit device in which circuit element is sealed by a sealing resin, wherein

a cavity portion is provided in the sealing resin, and the circuit element is stored in the cavity portion.

2. The device of Claim 1, wherein

the circuit element comprises a first circuit element sealed by the sealing resin and a second circuit element stored in the cavity portion, and the first circuit element and the second circuit element are electrically connected.

3. The device of Claim 1, wherein

connection terminals are provided in a peripheral portion of the cavity portion, and the circuit element is electrically connected to the connection terminals.

4. The device of Claim 2, wherein

the first circuit element is a semiconductor element to perform signal processing, and the second circuit element is a semiconductor element having a memory portion controlled by the first circuit element.

5. A circuit device comprising:

an island on which a first circuit element is affixed;

a plurality of leads which extend around the island and are electrically connected to the first circuit element;

a sealing resin which seals the first circuit element, island, and leads and forms a cavity portion; and

a second circuit element stored in the cavity portion.

6. The device of Claim 5, wherein

between the first circuit element and second circuit element, bridges for electrically connecting both circuit elements are provided.

7. The device of Claim 6, wherein

end portions of the leads and bridges are exposed in a peripheral portion of the cavity portion, and the second circuit element is mounted on the end portions.

8. The device of Claim 5, wherein

the first circuit element is a semiconductor element to perform signal processing, and the second circuit element is a semiconductor element having a memory portion controlled by the first circuit element.

9. A method for manufacturing a circuit device comprising :

sealing a first circuit element electrically connected to an external electrode with a sealing resin, and furthermore, providing a cavity portion in the sealing resin; and

storing a second circuit element in the cavity portion.

10. The method of Claim 9, wherein

after performing a test of the first circuit element, the second circuit element is stored.

11. The method of Claim 9, wherein

the second circuit element is placed on connection terminals provided in the cavity portion, and in a step of mounting the circuit device by a reflow, fixed fitting of the second circuit is performed.